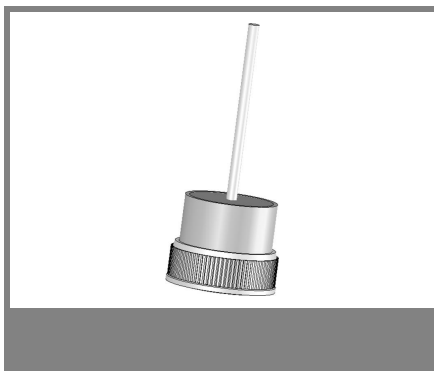


BYP 25A05 ... BYP 25K6



Silicon Press-Fit-Diodes

BYP 25A05...BYP 25K6

Forward Current: 25 A

Reverse Voltage: 50 to 600 V

Publish Data

Features

- max. solder temperature 260°C, max. 5s
- UL classification 94V-0
- Standard packaging: bulk

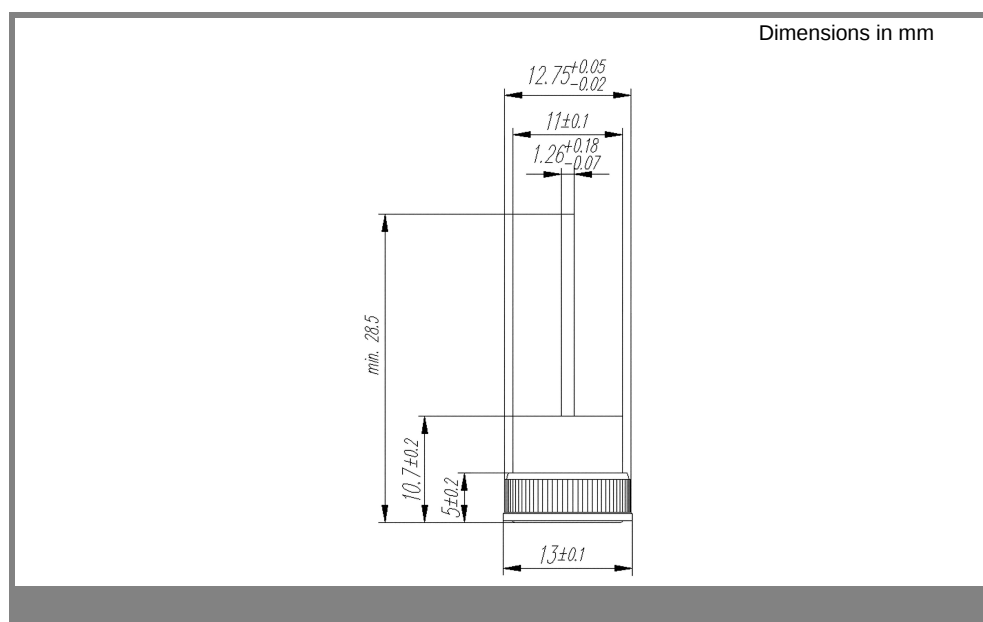
Mechanical Data

- Weight approx. 8 g
- Metal press-fit case with plastic cover
- Terminals: plated terminals solderable per IEC 68-2-20
- Mounting position : any

Type	Wired to ANODE	Wired to CATHODE	Repetitive peak reverse voltage V_{RRM} V	Surge peak reverse voltage V_{RSM} V	Maximum forward voltage $T_j = 25\text{ }^{\circ}\text{C}$ $I_F = 25\text{ A}$ V_F V
BYP 25	BYP 25A05	BYP 25K05	50	60	1,1
BYP 25	BYP 25A1	BYP 25K1	100	120	1,1
BYP 25	BYP 25A2	BYP 25K2	200	240	1,1
BYP 25	BYP 25A3	BYP 25K3	300	360	1,1
BYP 25	BYP 25A4	BYP 25K4	400	480	1,1
BYP 25	BYP 25A6	BYP 25K6	600	700	1,1

Absolute Maximum Ratings		$T_c = 25\text{ }^{\circ}\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
I_{FAV}	Max. averaged fwd. current, R-load, $T_c = 150\text{ }^{\circ}\text{C}$	25	A
I_{FRM}	Repetitive peak forward current $f > 15\text{ Hz}^{1)}$	90	A
I_{FSM}	Peak fwd. surge current 50 Hz half sinus-wave	270	A
I^2t	Rating for fusing, $t < 10\text{ ms}$	375	A ² s
R_{thA}	Thermal resistance junction to case	1	K/W
T_j	Operating junction temperature	- 50 ... + 215	$^{\circ}\text{C}$
T_s	Storage temperature	- 50 ... + 215	$^{\circ}\text{C}$

Characteristics		$T_c = 25\text{ }^{\circ}\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
I_R	Maximum leakage current, $T_A 25\text{ }^{\circ}\text{C}$; $V_R = V_{RRM}$	100	μA



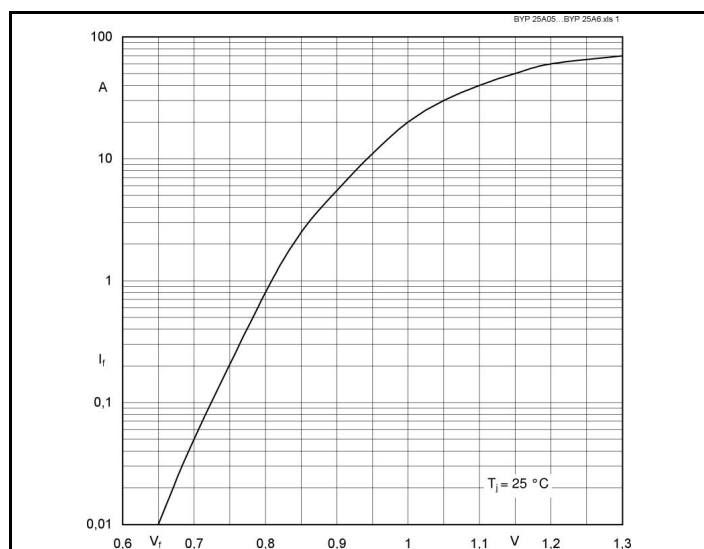


Fig. 1 Forward characteristic (typical values)

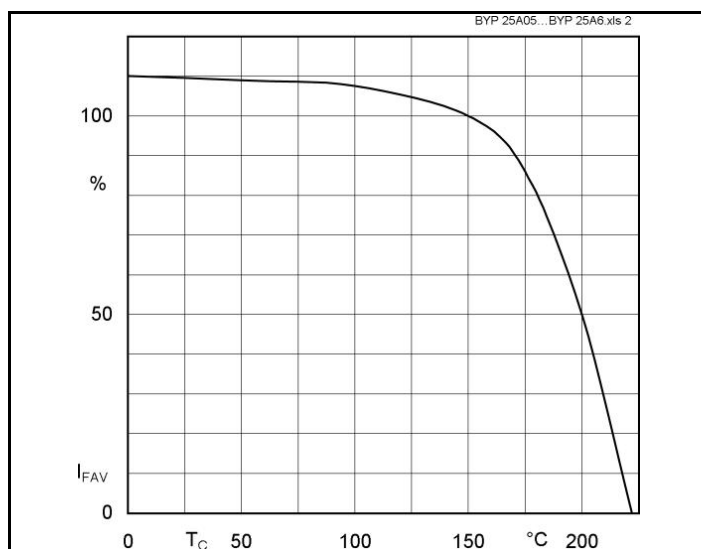


Fig. 2 Rated forward current vs. case temperature

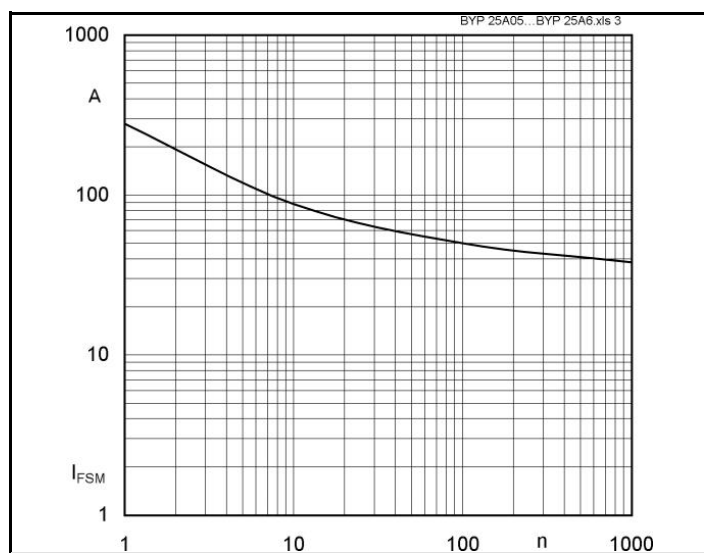


Fig. 3 Peak forward surge current versus number of cycles at 50 Hz